



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RRVC*VH75BAX	A	0959	2017-07-24
Amount	UoM	Unit type	ST ECOPACK Grade	
488.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	10.3-7.5-2.28	36	gull wing	
Comment	Package: PwSSO36 DUAL CHIP. MDF valid for CPs: VNHD7008AYTR and VNHD7008AY			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	die backside metal	76
Lead	6.01	soft solder	12316

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	RRVC*VH75BAX					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	Other inorganic materials	10.170	mg	supplier	die	Silicon (Si)	7440-21-3		9.471	mg	931268	19408
				supplier	metallization	Aluminium (Al)	7429-90-5		0.180	mg	17699	369
				supplier	metallization	Copper (Cu)	7440-50-8		0.065	mg	6391	133
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	1378	29
				supplier	metallization	Tungsten (W)	7440-33-7		0.168	mg	16519	344
				supplier	Passivation	Silicon Oxide	7631-86-9		0.104	mg	10226	213
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	295	6
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	885	18
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.037	mg	3638	76
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.003	mg	295	6
Leadframe	Copper & its alloys	161.652	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.116	mg	11406	237
				supplier	alloy	Copper (Cu)	7440-50-8		155.396	mg	961300	318434
				supplier	alloy	Iron (Fe)	7439-89-6		3.655	mg	22610	7490
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.220	mg	1360	451
				supplier	alloy	Zinc (Zn)	7440-66-6		0.191	mg	1182	391
				supplier	metallization	Silver (Ag)	7440-22-4		2.190	mg	13548	4488
Die attach	Other Organic Materials	0.338	mg	supplier	tape	Acrylic resin	9003-01-4		0.213	mg	630178	436
				supplier	tape	epoxy resin	Proprietary		0.125	mg	369822	256
				supplier	tape	epoxy resin	Proprietary		0.125	mg	369822	256
Soft solder	Solder	6.165	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	6.010	mg	974858	12316
				supplier	solder	Silver (Ag)	7440-22-4		0.093	mg	15085	191
				supplier	solder	Tin (Sn)	7440-31-5		0.062	mg	10057	127
				supplier	solder	Copper (Cu)	7440-50-8		3.441	mg	1000000	7051
Bonding wires	Other inorganic materials	3.441	mg	supplier	wire	Copper (Cu)	7440-50-8		3.441	mg	1000000	7051
				supplier	mold compound	Silica, vitreous	60676-86-0		260.912	mg	863999	534656
				supplier	mold compound	Epoxy Resin	25068-38-6		22.649	mg	75001	46412
				supplier	mold compound	Phenol Resin	29690-82-2		15.099	mg	50000	30941
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.510	mg	5000	3094
				supplier	mold compound	Quartz	14808-60-7		0.906	mg	3000	1857
Encapsulation	Other Organic Materials	301.982	mg	supplier	mold compound	Carbon black	1333-86-4		0.906	mg	3000	1857
				supplier	mold compound	Carbon black	1333-86-4		0.906	mg	3000	1857
Connections coating	Solder	4.252	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.252	mg	1000000	8713